

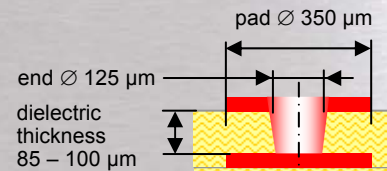


# HDI / Microvia Design Rules

download// [www.we-online.de/microvia](http://www.we-online.de/microvia) - design rules

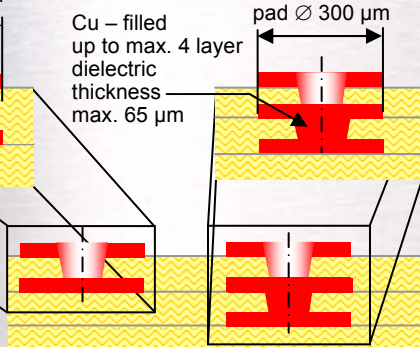


## microvia (for impedance controlled PCBs)



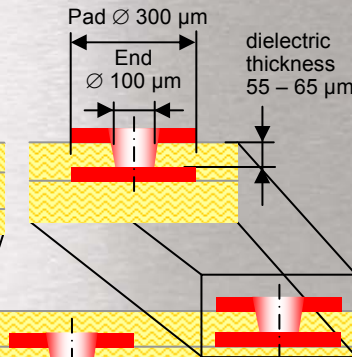
## stacked microvia (inner layer)

Cu - filled up to max. 4 layer  
dielectric thickness max. 65 µm

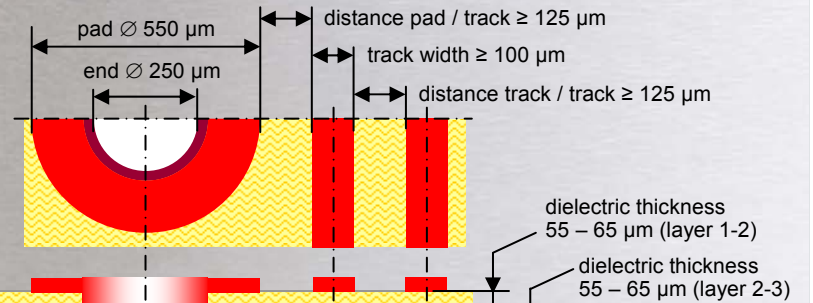


## standard - microvia

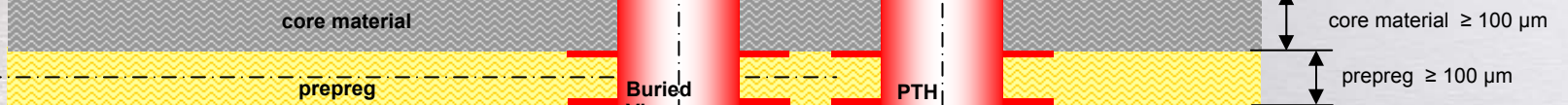
Pad Ø 300 µm  
End Ø 100 µm  
dielectric thickness 55 - 65 µm



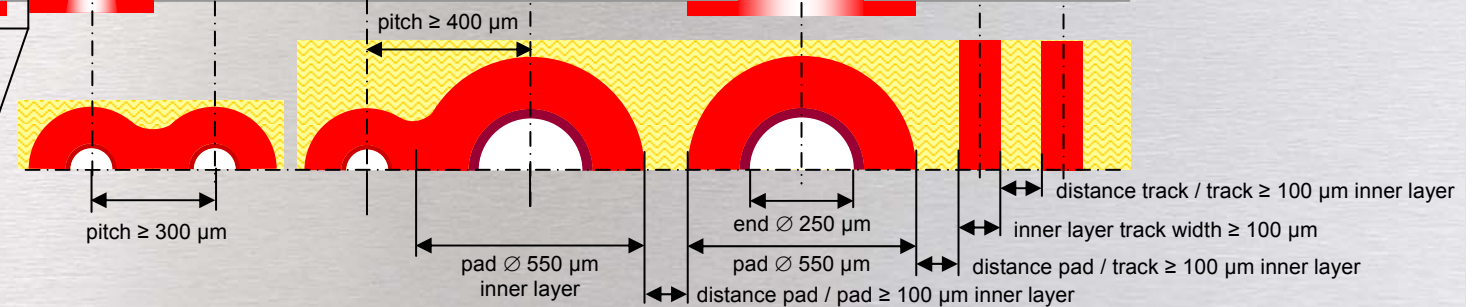
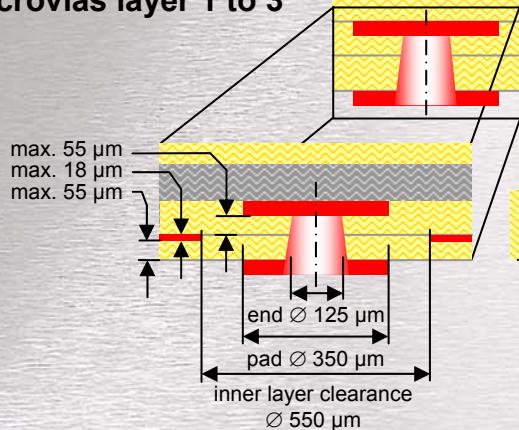
## outer layer layout



microvia aspect ratio = 1 : 0,8 (diameter / depth)



## microvias layer 1 to 3



## staggered microvias

## inner layer layout (up to 35 µm Cu thickness)